

TrustME® Secure Flash Memory Product Selection Guide 2025



winbond

BE A HIDDEN CHAMPION IN PROVIDING SUSTAINABLE SEMICONDUCTORS TO ENRICH HUMAN LIFE.

Winbond Vision Statement





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A trusted supplier of advanced memory products

About TrustME[®] Secure Flash

When an electronics product requires secure code storage, it needs certified TrustME[®] Secure Flash Memory from Winbond. The TrustME[®] family meets every system requirement, from the substantial protection required by simple IoT devices up to Common Criteria EAL 5+ certified memory for securing financial transactions.

W77Q and W77T	Secure Flash	Memory
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W75F Secure Memory Element

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POSITIONING & ADVANTAGES

A trusted supplier of advanced memory products

A Trusted Supplier of Advanced Memory Products

From R&D through advanced manufacturing to dedicated customer service, Winbond Electronics Corporation is a total memory solutions provider.

Winbond's customer-driven memory solutions are backed by deep expertise in

- R&D
- Product design
- Wafer fabrication and device packaging, assembly and testing
- Sales and technical support provided directly to the world's largest OEMs

Winbond's product portfolio consists of Customized Memory Solution, Code Storage Flash Memory, and TrustME[®] Secure Flash Memory. The company serves customers in communications, consumer electronics, automotive, industrial, computer peripherals markets and the IoT, supplying its products directly or via a global network of authorized distributors.

Winbond's headquarter is in the Central Taiwan Science Park. It operates 12-inch wafer fabs in Taichung and Kaohsiung in Taiwan.Subsidiaries in the USA, Japan, Israel, China, Hong Kong, and Germany perform marketing operations and provide direct support to customers.

Winbond's combination of advanced semiconductor technologies developed in-house and close relationships with customers support its position as a trusted supplier of memory products.

Trusted for Safety and High Quality

In high-technology products, the integrity of the software code and the reliable operation of memory devices are of critical importance. That's why Winbond's Quality Management Program governs every stage of a product's life, from its start in the R&D laboratory to manufacturing and device testing.

The program has three key elements:

E.	Quality Control	Meticulously monitors materials and production processes to check that they satisfy rigorous standards in automotive and industrial.
 	Reliability Assurance	Performs a comprehensive set of accelerated electrical, thermal, cycling, and other tests to verify the reliability of production units.
0 0 0 0 0 0	Failure Analysis	Investigates the causes of product failures and proposes corrective actions.

This is why Winbond is trusted by the world's largest manufacturers to provide on-time shipments of high-quality and high-reliability memory products.



Independently Verified Quality and Safety Performance

The data which Winbond provides to customers give direct assurance about the quality and reliability of its products. Comprehensive reliability test reports and quarterly average quality data are published on Winbond's website.

Customers can also take assurance from independent verification of the quality and safety of Winbond's products and processes:

Quality	Safety	Cyber-Security		
IATF 16949ISO 9001	ISO 26262ISO 45001	ISO 27001ISO 21434		
Environment		Others		
 ISO 14001 QC 080000 ISO 50001 	ISO 14064 SONY Green Partner ISO 46001	 RBA VAP Certificate AEC-Q100 Committee Member 		
CERTIFICATE C C CERTIFICATE C C C C CERTIFICATE C C C C C C C C C C C C C C C C C C C	SGS M CENTRAL CERTIFICATE S DE CENTRAL CERTIFICATE S DE CENTRAL CERTIFICATION S DE CENTRAL CENTRAL CERTIFICATION S DE CENTRAL CENTRAL CERTIFICATION S DE CENTRAL CENTRAL CERTIFICATION S DE CENTRAL CENTRAL CENTRAL CERTIFICATION S DE CENTRAL CENTRAL			



Reliability also extends to the supply chain: the Winbond Product Longevity Program guarantees a minimum 10-year lifetime for products supplied to automotive, industrial, consumer, medical, and industrial computing markets. Products supplied under this program are subject to extended product change notification, end-of-life and last-time buy arrangements.

TrustME® SECURE FLASH

When an electronics product requires secure code storage, it needs certified TrustME[®] Secure Flash Memory from Winbond. The TrustME[®] family meets every system requirement, from the substantial protection required by simple IoT devices up to Common Criteria EAL 5+ certified memory for securing financial transactions.

HRCKING

TrustME® Secure Flash

In today's interconnected world, electronic devices play an integral role in our daily lives. From consumer gadgets to critical infrastructure components, these devices rely heavily on flash memory for storing essential code and data. As such, safeguarding these assets from malicious cyber threats has become paramount.



Flash memories are the backbone of modern electronic platforms, housing vital assets such as code, private data, and company credentials. However, the ubiquity of these devices has also made them attractive targets for hackers. Accessing the content of flash devices or permanently modifying the system code stored in the flash are two of the more common attacks seen today. Standard flash devices have no means of protection from unauthorized access and modification.

Hackers can leverage these vulnerabilities to access end-users' private data, orchestrate large-scale attacks on corporate infrastructure via networking and IoT devices, and even engage in acts of sabotage and espionage against government infrastructure.

Recognizing the gravity of these challenges, Winbond Electronics Corporation has pioneered the development and introduction of a comprehensive range of TrustME[®] Secure Flash devices. These cutting-edge solutions are engineered to protect assets and create secure platforms for Winbond customers, safeguarding end users in various domains.

Winbond's Secure Flash devices service a wide array of applications, including consumer IoT, Industrial IoT, servers, networking, and automotive sectors. This versatility makes them an indispensable component in fortifying electronic devices across industries.

Winbond is deeply committed to safeguarding its customers against emerging cybersecurity threats. To prepare for the impending post-quantum era, Winbond has introduced Secure Flash devices fortified with post-quantum cryptography (PQC). This ensures that customers will continue to enjoy robust protection in an ever-evolving cybersecurity landscape.

Secure Flash Memory Enabling Trust & Providing Scalability

- Hardware security is the foundation of cyber security
- Secure storage is the core of hardware security
- Security by design



W77Q and W77T Secure Flash Memory

Provides substantial levels of security as defined by various Cybersecurity regulations. It is ideal for use in IoT end points and connected vehicles to protect code, data integrity, privacy and credentials.

The W77Q and W77T for IoT endpoints, automotive, networking and other types of connected devices provide important security functions, including hardware root-of-trust, secure boot, platform resilience, and strong data protection. The W77Q and W77T facilitate secure over-the-air software updates, even when the host processor is compromised.

Winbond's W77Q and W77T Secure Flash devices come equipped with an arsenal of features designed to ensure security:

Code and Data Protection	These devices offer robust protection for both code and data, making it exceedingly difficult for hackers to tamper with critical information.
Authentication	Winbond Secure Flash devices employ stringent authentication protocols, ensuring that only authorized actors and software layers gain access.
Secure Software Updates with Rollback Protection	The devices facilitate remote secure software updates while safeguarding against rollback attacks, ensuring that only legitimate updates are executed, leveraging Post-Quantum Cryptography, LMS (NIST800-208).
Platform Resiliency	Unauthorized code changes are automatically detected, enabling the system to recover to a secure state and disturbing potential cyber threats. Platform Resiliency of Winbond Secure Flash follows NIST SP 800-193 recommendations.
수 우 Secure Supply 승규 Chain	Winbond's Secure Flash devices guarantee the origin and integrity of flash content throughout the supply chain. This prevents content tampering and misconfiguration during platform assembly, transportation, and configuration, safeguarding against cyber adversaries.

Product Line	Description	Main Features and Security Level
W77Q	Quad SPI Secure Flash Memory	Main Features: • Code and Data Protection • Authentication • Secure OTA based on PQC ⁽² (LMS) • Platform Firmware Resiliency • Secure Supply Chain based on PQC ⁽² (LMS) • Extended RPMC ⁽² Safety and Substantial Security Level: • ISO 15408 CC EAL 2+ • SESIP Level 2 (with IEC 62443 and NIST 8259A Ready) • FIPS 140-3 CAVP and CMVP ⁽¹) • ISO 26262 Functional Safety ASIL-C Ready ⁽³) • ISO 21434 Automotive Cybersecurity ⁽³⁾
W77T	Octal SPI Secure Flash Memory	Main Features: • Quad SPI and x SPI Octal (200MHz) • Code and Data Protection • Authentication • Secure OTA based on PQC (LMS) • Platform Firmware Resiliency • Extended RPMC • Secure Supply Chain based on PQC (LMS) • High Reliability (Flash Array ECC and SPI CRC) Safety and Substantial Security Level: • ISO 15408 CC EAL 2+ (1 • FIPS 140-3 CAVP and CMVP (1 • ISO 26262 Functional Safety ASIL-D Ready (1 • ISO 21434 Automotive Cybersecurity (1

End-to-End Security Applications Example by Winbond Secure Flash Memory (W77Q)



Industrial Grade Support

Part No.	Density	STR Frequency (MHz)	DTR Frequency (MHz)	Operating Voltage (min) (V)	Operating Voltage (max) (V)	Operating Temp. (min) (°C)	Operating Temp. (max) (°C)	Package Type	Dimension	l/O (bit)	Interface Type	Mass Production	Security Features	Security Certifications
W77Q32JWSFIS	32 Mb	133	66	1.7	1.95	-40	85	SOIC-16	300 mil	4	SPI/Dual/Quad			
W77Q32JWSFIO	32 Mb	133	66	1.7	1.95	-40	85	SOIC-16	300 mil	4	SPI/Dual/Quad	\checkmark		
W77Q32JWSFIN	32 Mb	133	66	1.7	1.95	-40	85	SOIC-16	300 mil	4	SPI/Dual/Quad	\checkmark		
W77Q16JWSSIR	16 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	\checkmark		
W77Q16JWSSIQ	16 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	\checkmark		CC EAL2
W77Q32JWSSIR	32 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	\checkmark	Secure Boot	SESIP L2 (with IEC62443-4-2
W77Q32JWSSIQ	32 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad		Secure Storage	and NIST 8259A)
W77Q32JWSSIN	32 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	\checkmark	Secure Firmware Update (OTA)	ISO 21434
W77Q16JWZPIR	16 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	\checkmark	Platform Firmware Resiliency	ISO 26262 ASIL-C Ready
W77Q16JWZPIQ	16 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad			FIPS 140-3 CAVP
W77Q32JWZPIR	32 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	\checkmark		
W77Q32JWZPIQ	32 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	\checkmark		
W77Q32JWXGIR	32 Mb	133	66	1.7	1.95	-40	85	XSON-8	4x4 mm	4	SPI/Dual/Quad	\checkmark		
W77Q32JWXGIQ	32 Mb	133	66	1.7	1.95	-40	85	XSON-8	4x4 mm	4	SPI/Dual/Quad	\checkmark		

Winbond shall have the right to modify the status and schedule of this product at any time without notice.

W77Q and W77T Secure Flash Memory

Industrial Grade Support

Part No.	Density	STR Frequency (MHz)	DTR Frequency (MHz)	Operating Voltage (min) (V)	Operating Voltage (max) (V)	Operating Temp. (min) (°C)	Operating Temp. (max) (°C)	Package Type	Dimension	VO (bit)	Interface Type	Mass Production	Security Features	Security Certifications	
W77Q64JWSSIR	64 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	√			
W77Q64JWSSIQ	64 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	\checkmark			
W77Q128JWSIR	128 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	\checkmark			
W77Q128JWSIQ	128 Mb	133	66	1.7	1.95	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	\checkmark			
W77Q64JWZPIR	64 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	\checkmark			
W77Q64JWZPIQ	64 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	\checkmark			
W77Q128JWPIR	128 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	\checkmark			
W77Q128JWPIQ	128 Mb	133	66	1.7	1.95	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	\checkmark			
W77Q128JWBIS	128 Mb	133	66	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark			
W77Q128JWBIO	128 Mb	133	66	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark			
W77Q128JWBJS	128 Mb	133	66	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark			
W77Q128JWBJO	128 Mb	133	66	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark			
W77Q64JWTBIS	64 Mb	133	66	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark			
W77Q64JWTBIO	64 Mb	133	66	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark		CC EAL2	
W77Q64JWTBJS	64 Mb	133	66	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark	Secure Boot	SESIP L2 (with IEC62443-4-2	
W77Q64JWTBJO	64 Mb	133	66	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	\checkmark	Secure Storage	and NIST 8259A)	
W77Q64JVSSIR	64 Mb	133	66	2.7	3.6	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	V	Secure Firmware Update (OTA)	ISO 21434	
W77Q64JVSSIQ	64 Mb	133	66	2.7	3.6	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	V	Plationn Finnware Resiliency	FIPS 140-3 CMVP (1	
W77Q128JVSIR	128 Mb	133	66	2.7	3.6	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	V			
W77Q128JVSIQ	128 Mb	133	66	2.7	3.6	-40	85	SOIC-8	208 mil	4	SPI/Dual/Quad	V			
W77Q64JVZPIR	64 Mb	133	66	2.7	3.6	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	V			
W//Q64JVZPIQ	64 Mb	133	66	2.7	3.6	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	V			
W77Q128JVPIR	128 Mb	133	66	2.7	3.6	-40	85	WSON-8	6x5 mm	4	SPI/Dual/Quad	V			
W77Q128JVPIQ	128 Mb	133	66	2.7	3.6	-40	85		6x5 mm	4	SPI/Dual/Quad	V			
	120 IVID	133	66	2.7	3.0	-40	60 95	TEPCA 24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	V			
W770128JVBI0	120 IVID	133	66	2.7	3.0	-40	105	TEBCA 24 (5x5)	5x5-1 mm	4		V			
W770128 IVB I0	128 Mb	133	66	2.7	3.6	-40	105	TEBGA-24 (5x5)	5x5-1 mm	4		V			
W77Q64.IVTBIS	64 Mb	133	66	27	3.6	-40	85	TEBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	v 			
W77Q64JVTBIO	64 Mb	133	66	2.7	3.6	-40	85	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	V			
W77Q64JVTBJS	64 Mb	133	66	2.7	3.6	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	V			
W77Q64JVTBJO	64 Mb	133	66	2.7	3.6	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	√			
W77Q25NWSFIE	256 Mb	166	166	1.7	1.95	-40	85	WSON-8	8x6 mm	4	SPI/Quad	2025			
W77Q25NWSEIE	256 Mb	166	166	1.7	1.95	-40	85	SOIC-16	300 mil	4	SPI/Quad	2025			
W77Q25NWSBIE	256 Mb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Quad	2025			
W77Q51NWDFIE	512 Mb	166	166	1.7	1.95	-40	85	SOIC-16	300 mil	4	SPI/Quad	2025			
W77Q51NWDEIE	512 Mb	166	166	1.7	1.95	-40	85	WSON-8	8x6 mm	4	SPI/Quad	2025			
W77Q51NWDBIE	512 Mb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Quad	2025	Conver Doot		
W77Q25NWSFIN	256 Mb	166	166	1.7	1.95	-40	85	SOIC-16	300 mil	4	SPI/Quad	2025	Secure Storage	CC EAL2	
W77Q25NWSEIN	256 Mb	166	166	1.7	1.95	-40	85	WSON-8	8x6 mm	4	SPI/Quad	2025	Secure Firmware Update Using LMS	SESIP (with IEC62443-4-2	
W77Q25NWSFJE	256 Mb	166	166	1.7	1.95	-40	105	SOIC-16	300 mil	4	SPI/Quad	2025	Asymmetric Cryptography	and NIST 8259A)	
W77Q25NWSEJE	256 Mb	166	166	1.7	1.95	-40	105	WSON-8	8x6 mm	4	SPI/Quad	2025	Platform Firmware Resiliency	FIPS PUB 180-3 CMVP	
W77Q25NWSBJE	256 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Quad	2025			
W77Q51NWDFJE	512 Mb	166	166	1.7	1.95	-40	105	SOIC-16	300 mil	4	SPI/Quad	2025			
W77Q51NWDEJE	512 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Quad	2025			
W77Q51NWDBJE	512 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Quad	2025			
W77Q25NWSFJN	256 Mb	166	166	1.7	1.95	-40	105	SOIC-16	300 mil	4	SPI/Quad	2025			
W77Q25NWSEJN	256 Mb	166	166	1.7	1.95	-40	105	WSON-8	8x6 mm	4	SPI/Quad	2025			

⁽¹ Certification in progress Winbond shall have the right to modify the status and schedule of this product at any time without notice.

Part No.	Density	STR Frequency (MHz)	DTR Frequency (MHz)	Operating Voltage (min) (V)	Operating Voltage (max) (V)	Operating Temp. (min) (°C)	Operating Temp. (max) (°C)	Package Type	Dimension	VO (bit)	Interface Type	Mass Production	Security Features	Security Certifications
W77T25NWSBIE	256 Mb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Secure Boot	
W77T51NWDBIE	512 Mb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Secure Storage	CC EAL2
W77T01NWQBIE	1 Gb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	PQC	SESIP (with IEC62443-4-2
W77T25NWSBIO	256 Mb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Asymmetric Cryptography Platform Firmware Resiliency	ISO 21434
W77T51NWDBIO	512 Mb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	RPMC	FIPS PUB 180-3 CMVP
W77T01NWQBIO	1 Gb	200	200	1.7	1.95	-40	85	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Built-in ECC and SPI CRC for Safety	

Automotive Grade Support

WY77GLAWSAR 16 Mb 13 66 17 165 400 13 66 17 165 40 13 66 17 155 40 165 501-48 206 mil 4 SPDLau/Duad 4 WY7032AWSSAR 32 Mb 13 66 17 155 40 165 501-48 208 mil 4 SPDLau/Duad 4 WY7032AWSSAR 32 Mb 13 66 17 155 40 165 WSON8 6.5 mm 4 SPDLau/Duad 4 SPDLau/Duad 4 WY7032AWZPAR 16 Mb 13 66 17 155 40 165 WSON8 6.5 mm 4 SPDLau/Duad	Part No.	Density	STR Frequency (MHz)	DTR Frequency (MHz)	Operating Voltage (min) (V)	Operating Voltage (max) (V)	Operating Temp. (min) (°C)	Operating Temp. (max) (ºC)	Package Type	Dimension	l/O (bit)	Interface Type	Mass Production	Security Features	Security Certifications
197701 1984 131 66 17 1.85 -00 105 SOC-3 208 ml 4 SPIDualQuad 1 1977032LWSAS 324b 133 66 1.7 1.5 -0 105 SOC-3 208 ml 4 SPIDualQuad 1 1977032LWSAS 324b 133 66 1.7 1.5 -0 105 WSONB 6.5 mm 4 SPIDualQuad 1 1977032LWZPAS 224b 133 66 1.7 1.5 -0 105 WSONB 6.5 mm 4 SPIDualQuad 1 1977032LWZPAS 224b 133 66 1.7 1.5 -0 105 SOC-8 208 ml 4 SPIDualQuad 1 1977032LWZPAS 24bb 133 66 1.7 1.5 -0 105 SOC-8 208 ml 4 SPIDualQuad 205 1977032LWZPAS 24bb 133 66 1.7 1.5 -0 105 SOC-8 208 ml 4 SPIDualQuad 205 Socurue Bod Socurue Bod	W77Q16JWSSAR	16 Mb	133	66	1.7	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	√		
NYT70222/NSAR 21 Mit 33 66 7 1.8 -00 05 SOC-4 20 8 mit 4 SPIDualQuad 4 WT7032N/NSAR 61 Mit 133 66 7 1.5 40 05 WSONA 6.6 mm 4 SPIDualQuad 4 WT703LN/ZPAR 16 Mit 133 66 7 1.6 40 105 WSONA 6.6 mm 4 SPIDualQuad 4 WT703LN/ZPAR 32 Mit 13 66 1.7 1.5 40 105 VSONA 6.6 mm 4 SPIDualQuad 4 WT703LN/ZPAR 64Mit 13 66 1.7 1.5 40 105 SOCA 208 mit 4 SPIDualQuad 205 WT703LN/XPAR 128Mit 13 66 1.7 1.5 40 105 SOCA 208 mit 4 SPIDualQuad 205 WT703LN/XPAR 128Mit 13 66 1.7 1.5 40 105 <td>W77Q16JWSSAQ</td> <td>16 Mb</td> <td>133</td> <td>66</td> <td>1.7</td> <td>1.95</td> <td>-40</td> <td>105</td> <td>SOIC-8</td> <td>208 mil</td> <td>4</td> <td>SPI/Dual/Quad</td> <td></td> <td></td> <td></td>	W77Q16JWSSAQ	16 Mb	133	66	1.7	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad			
UPT/D22_WISAQ 28 MP 313 66 1.7 1.96 40 105 SOIC-8 28 PID_LaQUad 4 SPID_LaQUad 4 VIT7016_WIZPAR 16 Mo 133 66 1.7 1.86 40 105 WSON-8 65 frm 4 SPID_LaQUad 4 VIT7028_WIZPAR 313 66 1.7 1.86 40 105 WSON-8 65 frm 4 SPID_LaQUad 4 VIT7028_WIZPAR 32 M0 133 66 1.7 1.86 105 WSON-8 65 frm 4 SPID_LaQUAd 4 SPID_LaQUAd 4 SPID_LaQUAd 4 SPID_LaQUAd 4 SPID_LaQUAd 225 VIT7028_WISPAR 64M0 133 66 1.7 15 40 105 SOIC-8 20 mil 4 SPID_LaQUAd 225 Source Storage Source Storage VIT7028_WISPAR 128M0 133 66 1.7 15 40 105 WSONA 8 SPID_LaQUAd 2	W77Q32JWSSAR	32 Mb	133	66	1.7	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	V		00 541 0
VIT701GLW/ZPAR 16 Mb 133 66 1.7 1.96 40 105 WSON-86 6:6 mm 4 SPIDual/Quad V VIT701GLW/ZPAR 2.0M 133 66 1.7 1.96 40 105 WSON-86 6:6 mm 4 SPIDual/Quad V VIT702SLW/ZPAR 2.0M 133 66 1.7 1.96 40 105 WSON-86 6:6 mm 4 SPIDual/Quad V VIT702SLW/ZPAR 2.2M 133 66 1.7 1.96 10 105 SSON-86 4.4 mm 4 SPIDual/Quad 2.25 VIT702SLW/SAR 64Mb 133 66 1.7 1.96 40 105 SOIC-8 2.08 mil<4	W77Q32JWSSAQ	32 Mb	133	66	1.7	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	√		CC EAL2 SESIPT 2 (with IEC62443-4-2
9777016LW2PA0 16 M0 133 66 17 156 40 105 WSON48 65.6 mm 4 SPIDua/Quad V 9777032LW2PAR 32 M0 133 66 17 156 40 105 WSON48 65.6 mm 4 SPIDua/Quad V 9777032LW2PAR 32 M0 133 66 17 156 40 105 WSON48 64.0 mm 4 SPIDua/Quad V 9777032LW3AR 32 M0 133 66 17 156 105 SSOL48 208 mil 4 SPIDua/Quad 225 977704LW3SAR 64M0 133 66 17 156 105 SOL48 208 mil 4 SPIDua/Quad 225 9777064LW2PAQ 64Mb 133 66 17 156 WSON48 65 mm 4 SPIDua/Quad 225 Secure Elon Secure Firmware Udate (01A) 977024LW2PAQ 128Mb 133 66 17 156 105 WSON48 65 mm 4 SPIDua/Quad 225 Secure Firmware Udate (01A) SECUR	W77Q16JWZPAR	16 Mb	133	66	1.7	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	√		and NIST 8259A)
IVT7032JWZPAQ 32 Mb 133 66 17 195 40 105 WSON+8 6xfmm 4 SPIDualQuad 1 V77032JWZPAQ 32 Mb 133 66 17 135 40 105 XSON+8 4x4 mm 4 SPIDualQuad 1 V77032JWZPAQ 32 Mb 133 66 17 135 40 105 XSON+8 4x4 mm 4 SPIDualQuad 1 V7704LVXSAQ 64 Mb 133 66 17 135 40 105 SOIC-8 208 mil 4 SPIDualQuad 2025 V7704LVXSAQ 128Mb 133 66 17 135 40 105 SOIC-8 208 mil 4 SPIDualQuad 2025 Secure Bond Secure Stronge Secure Stro	W77Q16JWZPAQ	16 Mb	133	66	1.7	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	√		ISO 21434
WT7032JWZPAQ 32 Mb 133 66 1.7 1.95 40 105 WSON-8 6.6 mm 4 SPIDualQuad V WT7032JWGQA 32 Mb 133 66 1.7 1.5 40 105 XSON-8 4.4 mm 4 SPIDualQuad V WT7032JWGQA 32 Mb 133 66 1.7 1.5 40 105 SOIC-8 208 mil 4 SPIDualQuad 2025 WT704LWSAR 128 Mb 133 66 1.7 1.95 40 106 SOIC-8 208 mil 4 SPIDualQuad 2025 WT704LWSAR 128 Mb 133 66 1.7 1.95 40 105 WSON-8 66 mm 4 SPIDualQuad 2025 Secure Boot WT704LWPAQ 128 Mb 133 66 1.7 1.95 40 105 FPEGA-42 (Sx5) 5x5-1 mm 4 SPIDualQuad 2025 Secure Boot Secure Stratege Secure Stratege Stratege Stratege Stratege Stratege Stratege Stratege Stratege Stratege	W77Q32JWZPAR	32 Mb	133	66	1.7	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	√		ISO 26262 ASIL-C Ready
W77CQ32,WWGAP 32 Mb 133 66 1.7 1.95 -40 105 XSON+8 4.44 mm 4 SPIDual/Quad V W77CQ42,WWGAQ 32 Mb 133 66 1.7 1.9 40 105 SOIC-8 228 mil 4 SPIDual/Quad 225 W77CQ4,WSAQ 124Mb 133 66 1.7 1.9 40 105 SOIC-8 228 mil 4 SPIDual/Quad 225 W77CQ4,WSAQ 124Mb 133 66 1.7 1.9 40 105 SOIC-8 228 mil 4 SPIDual/Quad 225 W77CQ4,WSAQ 124Mb 133 66 1.7 1.9 40 105 SOIC-8 228 mil 4 SPIDual/Quad 225 W77CQ4,WZPAR 64Mb 133 66 1.7 1.9 40 105 WSON+8 6:5 mm 4 SPIDual/Quad 225 Secure Storage W77CQ128,WFAQ 128Mb 133 66 1.7 1.9 40 105 TFIDA-24 (5:5) 5:5 1 mm 4 SPIDual/Quad	W77Q32JWZPAQ	32 Mb	133	66	1.7	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	√		FIPS 140-3 CAVP
W77CQ42UWSAQ 32 Mb 33 66 1.7 1.95 40 105 XSON-8 208 ml 4 SPIDualQuad V W77CQ4LVSAR 64Mb 133 66 1.7 1.95 40 105 SOIC-8 208 ml 4 SPIDualQuad 2025 W77CQ4LVSAR 128Mb 133 66 1.7 1.95 40 105 SOIC-8 208 ml 4 SPIDualQuad 2025 W77CQ4LVSAR 128Mb 133 66 1.7 1.95 40 105 SOIC-8 208 ml 4 SPIDualQuad 2025 W77CQ4LVZPAQ 64Mb 133 66 1.7 1.95 40 105 WSON-8 65 mm 4 SPIDualQuad 2025 Secure Boot W77CQ4LVZPAQ 128Mb 133 66 1.7 1.95 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPIDualQuad 2025 Secure Boot Nort 100 Nort 1	W77Q32JWXGAR	32 Mb	133	66	1.7	1.95	-40	105	XSON-8	4x4 mm	4	SPI/Dual/Quad	, √		
W77064JVSSAR 64Mb 133 66 1.7 1.95 -40 105 SOIC-8 208mil 4 SPI/Dual/Ouad 2025 W77064JVSSAQ 64Mb 133 66 1.7 1.95 40 105 SOIC-8 208mil 4 SPI/Dual/Ouad 2025 W770128JVSAQ 128Mb 133 66 1.7 1.95 40 105 SOIC-8 208 mil 4 SPI/Dual/Ouad 2025 W770128JVSAQ 128Mb 133 66 1.7 1.95 40 105 WSON-8 6.5 mm 4 SPI/Dual/Ouad 2025 Secure Firmware Public (OTA) W770128JVPAQ 128Mb 133 66 1.7 1.95 40 105 WSON-8 6.5 mm 4 SPI/Dual/Ouad 2025 Public Firmware Resiliency W77064JWSAA 128Mb 133 66 1.7 1.95 40 105 TBGA-24 (55) 5.5 mm 4 SPI/Dual/Ouad 2025 Public Micro2025 SESIP 1.2 (With IEC62443-4:2 SESIP 1.2 (With IEC62443-4:2 SESIP 1.2 (With IEC62443-4:2 SESIP 1.2 (With IEC62443-4:2<	W77Q32JWXGAQ	32 Mb	133	66	1.7	1.95	-40	105	XSON-8	4x4 mm	4	SPI/Dual/Quad	1		
W77064JVSSAQ 64Mb 133 66 1.7 1.95 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77012BJVSAR 128Mb 133 66 1.7 1.95 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77064JVZPAR 64Mb 133 66 1.7 1.95 40 105 WSON-8 6.5 mm 4 SPI/Dual/Quad 2025 Secure Storage W77012BJVPAQ 128Mb 133 66 1.7 1.95 40 105 WSON-8 6.5 mm 4 SPI/Dual/Quad 2025 Secure Storage W77012BJVPAQ 128Mb 133 66 1.7 1.95 40 105 TBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Secure Firmware Resiliency W77064JVTBAS 64Mb 133 66 1.7 1.95 40 105 TBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Secure Firmware Resiliency W77064JWSAQ 64Mb 133 66 2.7 3.6 </td <td>W77Q64JVSSAR</td> <td>64Mb</td> <td>133</td> <td>66</td> <td>1.7</td> <td>1.95</td> <td>-40</td> <td>105</td> <td>SOIC-8</td> <td>208 mil</td> <td>4</td> <td>SPI/Dual/Quad</td> <td>2025</td> <td></td> <td></td>	W77Q64JVSSAR	64Mb	133	66	1.7	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		
WT70128JVSAR 128Mb 133 66 1.7 1.95 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT70128JVSAQ 128Mb 133 66 1.7 1.95 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7064JVZPAQ 64Mb 133 66 1.7 1.95 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 Secure Boot WT70128JVPAQ 128Mb 133 66 1.7 1.95 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 Secure Firmware Update (OTA) WT70128JVPAQ 128Mb 133 66 1.7 1.95 40 105 TFBGA-24 (Sx5) Sx5-1 mm 4 SPI/Dual/Quad 2025 Secure Firmware Update (OTA) All NIST 825A) INS 1.44 SPI/Dual/Quad 2025 Secure Firmware Update (OTA) SESA) SESA 1 SPI/Dual/Quad 2025 SEST SESA 1 SESA 1 SPI/Dual/Quad 2025 SESA 1 SESA 1 SESA 1 SESA 1 SESA 1	W77Q64JVSSAQ	64Mb	133	66	1.7	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		
WT70123U/SAQ 128/b 133 66 1.7 1.95 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7064/WZPAR 64/hb 133 66 1.7 1.95 40 105 WSON-8 6.5 mm 4 SPI/Dual/Quad 2025 Secure Boot WT70128/WPAR 128/hb 133 66 1.7 1.95 40 105 WSON-8 6.55 mm 4 SPI/Dual/Quad 2025 Secure Boot WT70128/WPAR 128/hb 133 66 1.7 1.95 40 105 WSON-8 6.55 mm 4 SPI/Dual/Quad 2025 WT7064/WBAS 128/hb 133 66 1.7 1.95 40 105 TBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 WT7064/WBAS 64/hb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7064/WFAR 64/hb <t< td=""><td>W77Q128JVSAR</td><td>128Mb</td><td>133</td><td>66</td><td>1.7</td><td>1.95</td><td>-40</td><td>105</td><td>SOIC-8</td><td>208 mil</td><td>4</td><td>SPI/Dual/Quad</td><td>2025</td><td></td><td></td></t<>	W77Q128JVSAR	128Mb	133	66	1.7	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		
WT7064JVZPAR 64Mb 133 66 1 1.95 40 105 WS0N-8 6x5 mm 4 SPI/Dual/Quad 2225 Secure Boot WT7064JVZPAC 64Mb 133 66 1.7 1.95 40 105 WS0N-8 6x5 mm 4 SPI/Dual/Quad 2025 Secure Boot WT70128JVPAC 128Mb 133 66 1.7 1.95 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Secure Boot WT7064JVTBAS 64Mb 133 66 1.7 1.95 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Platform Firmware Update (OTA) WT7064JVTBAS 64Mb 133 66 1.7 1.95 40 105 SDIC-8 208 mil 4 SPI/Dual/Quad 2025 SU1434 SDIC-8 208 mil 4 SPI/Dual/Quad 2025 SDI434 SDI 2662 ASIL-7 A0 105 SDIC-8 208 mil 4 SPI/Dual/Quad 2025 SDI434 SDI 2662 ASIL-7 A0 10	W770128.IVSA0	128Mb	133	66	17	1.95	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		
WT7064/WZPAQ 64Mib 138 66 17 1.95 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 Secure Boot WT70128.WPAR 128Mib 133 66 1.7 1.95 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 Secure Storage WT70128.WPAR 128Mib 133 66 1.7 1.95 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Secure Storage Secure Storage CC EAL2 WT7064.WT8AO 128Mib 133 66 1.7 1.95 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Secure Storage and NIST 8259A) ISO 21434 WT7064.WYSAR 64Mib 133 66 2.7 36 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 ISO 21434 ISO 26622 ASIL-C Ready ISO 26622 ASIL-C Ready ISO 26622 ASIL-C Ready ISO 2662 ISO 26662 ASIL-C Ready ISO 26662 ASIL-C Ready ISO 26662 ASIL-C Ready ISO 26662 ASIL-C Ready ISO 26662 ASIL-C	W77064.IV7PAR	64Mb	133	66	17	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025		
WT70128JVPAR 128Mb 133 66 1.7 1.95 -40 105 WS0N-8 6x5 mm 4 SPI/Dual/Quad 2025 Secure Storage Secure Storage WT70128JVPAQ 128Mb 133 66 1.7 1.95 -40 105 WS0N-8 6x5 mm 4 SPI/Dual/Quad 2025 Secure Storage Secure Storage CC EAL2 WT70128JVPAQ 128Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Platform Firmware Update (OTA) WT7064JWFAS 64Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 WT7064JWFSAR 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7064JWZPAR 64Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 Soid Soid Soid Soid	W77Q64JVZPAQ	64Mb	133	66	1.7	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025	Colored Doort	
W77Q128JVPAQ 128Mb 133 66 1.7 1.95 -40 105 WSON-8 6x5mm 4 SPI/Dual/Quad 2025 Secure Firmware Update (OTA) W77Q128JVBAS 128Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 Secure Firmware Update (OTA) W77Q128JVBAS 128Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAO 64Mb 133 66 1.7 1.95 -40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q64JWSAQ 64Mb 133 66 2.7 3.6 -40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 SOIC-8 208	W77Q128JVPAR	128Mb	133	66	1.7	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025	Secure Boot	
W77Q128UVBAS 128Mb 133 66 1.7 1.95 40 105 TFBGA-24 (5x) 5x5-1mm 4 SPI/Dual/Quad 2025 Platform Firmware Resiliency W77Q128UVBAO 128Mb 133 66 1.7 1.95 40 105 TFBGA-24 (5x) 5x5-1mm 4 SPI/Dual/Quad 2025 W77Q64VTBAS 64Mb 133 66 1.7 1.95 40 105 TFBGA-24 (5x) 5x5-1mm 4 SPI/Dual/Quad 2025 W77Q64VWTBAS 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q64JWZPAR 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q64JWZPAR 64Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAR 128Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4<	W77Q128JVPAQ	128Mb	133	66	1.7	1.95	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025	Secure Firmware Update (OTA)	
W77Q128JWBAO 128Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 m 4 SPI/Dual/Quad 2025 W77O64JWTBAO 64Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 m 4 SPI/Dual/Quad 2025 W77O64JWTBAO 64Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 m 4 SPI/Dual/Quad 2025 W77O64JWTSAO 64Mb 133 66 2.7 3.6 -40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77O128JWSAO 128Mb 133 66 2.7 3.6 -40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77O128JWRAO 128Mb 133 66 2.7 3.6 -40 105 WSON-8 6.5 mm 4 SPI/Dual/Quad 2025 W77O128JWRAO 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dua	W77Q128JVBAS	128Mb	133	66	1.7	1.95	-40	105	TEBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025	Platform Firmware Resiliency	
WT7064.WTBAS 64Mb 13 66 1.7 1.9 40 105 TFBGA-24 (5x5) 5x5.1 mm 4 SPI/Dual/Quad 2025 SSS1PL L(with) EC62443-4.2 and NIST 8259A) WT7064.WTSAA 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 SSS1PL	W77Q128JVBAQ	128Mb	133	66	1.7	1.95	-40	105	TEBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025		
W77064.JVTBA0 64Mb 133 66 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77064.JWSSAR 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77064.JWSSAR 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W770128.JWSAR 128Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77064.JWZPAR 64Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W770128.JWPAR 128Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W770128.JWBA0 128Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad	W77Q64JVTBAS	64Mb	133	66	1.7	1.95	-40	105	TEBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025		CC EAL2
WT7Q64.WVSSAR 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7Q64.WVSSAR 128Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7Q128.WSAQ 128Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7Q64.WZPAR 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 WT7Q64.WZPAR 64Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 WT7Q128.WPAQ 128Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 WT7Q128.WPAQ 128Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2	W77Q64JVTBAQ	64Mb	133	66	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025		and NIST 8259A)
W77Q64JWSSAQ 64Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q128JWSAQ 128Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q128JWSAQ 128Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q64JWZPAR 64Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q128JWBAQ 128Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 202	W77Q64JWSSAB	64Mb	133	66	2.7	3.6	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		ISO 21434
W77Q128JWSAR 128Mb 133 66 2.7 3.6 -40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q128JWSAQ 128Mb 133 66 2.7 3.6 -40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q64JWZPAR 64Mb 133 66 2.7 3.6 -40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 -40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q128JWBAS 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q128JWBAS 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad </td <td>W77Q64JWSSAQ</td> <td>64Mb</td> <td>133</td> <td>66</td> <td>2.7</td> <td>3.6</td> <td>-40</td> <td>105</td> <td>SOIC-8</td> <td>208 mil</td> <td>4</td> <td>SPI/Dual/Quad</td> <td>2025</td> <td></td> <td>ISO 26262 ASIL-C Ready</td>	W77Q64JWSSAQ	64Mb	133	66	2.7	3.6	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		ISO 26262 ASIL-C Ready
W77Q128JWSAQ 128Mb 133 66 2.7 3.6 40 105 SOIC-8 208 mil 4 SPI/Dual/Quad 2025 W77Q64JWZPAR 64Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAR 128Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAR 128Mb 133 66 2.7 3.6 40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAR 128Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q128JWBAO 128Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAO 64Mb 133 66 2.7 3.6 40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Dual/Quad	W77Q128JWSAR	128Mb	133	66	2.7	3.6	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		FIPS 140-3 CMVP (1
W77Q64JWZPAR 64Mb 133 66 2.7 3.6 -40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q64JWZPAQ 64Mb 133 66 2.7 3.6 -40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 -40 105 WSON-8 6x5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAS 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAS 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Q	W77Q128JWSAQ	128Mb	133	66	2.7	3.6	-40	105	SOIC-8	208 mil	4	SPI/Dual/Quad	2025		
W77Q64JWZPAQ 64Mb 133 66 2.7 3.6 -40 105 WSON-8 6.5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAR 128Mb 133 66 2.7 3.6 -40 105 WSON-8 6.5 mm 4 SPI/Dual/Quad 2025 W77Q128JWPAQ 128Mb 133 66 2.7 3.6 -40 105 WSON-8 6.5 mm 4 SPI/Dual/Quad 2025 W77Q128JWBAS 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAS 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAS 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77T25NWSBAE 256 Mb 100 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal	W77Q64JWZPAR	64Mb	133	66	2.7	3.6	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025		
W7TQ128JWPAR 128Mb 133 66 2.7 3.6 -40 105 WSON-8 6.45 mm 4 SPI/Dual/Quad 2025 W7TQ128JWPAQ 128Mb 133 66 2.7 3.6 -40 105 WSON-8 6.45 mm 4 SPI/Dual/Quad 2025 W7TQ128JWBAS 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W7TQ128JWBAO 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W7TQ64JWTBAO 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W7T725NWSBAE 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Boot Secure Boot Secure Firmware Update Using Link Secure Firmware Update Using Link Secure Firmware Update Using Link NO NIST 8259A) So 21434 NIST 82	W77Q64JWZPAQ	64Mb	133	66	2.7	3.6	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025		
WT7Q128JWPAQ 128 Mb 133 66 2.7 3.6 -40 105 WS0N-8 6.45 mm 4 SPI/Dual/Quad 2025 WT7Q128JWBAS 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 WT7Q128JWBAO 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 WT7Q64JWTBAO 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 WT7T25NWSBAE 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 WT7T25NWSBAD 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Boot Secure Firmware Update Using U	W77Q128JWPAR	128Mb	133	66	2.7	3.6	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025		
W77Q128JWBAS 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q128JWBAO 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAO 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAO 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77T25NWSBAE 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Bot Secure Storage Secure Firmware Update Using Lising	W77Q128JWPAQ	128Mb	133	66	2.7	3.6	-40	105	WSON-8	6x5 mm	4	SPI/Dual/Quad	2025		
W77Q128JWBAO 128Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAS 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAO 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77T25NWSBAE 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Boot W77T25NWSBAO 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Firmware Update Using Link NIST 8259A) So 21434 NIST 8259A) So 2143	W77Q128JWBAS	128Mb	133	66	2.7	3.6	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025		
W77Q64JWTBAS 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77Q64JWTBAO 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77T25NWSBAE 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Boot Secure Boot Secure Storage Secure Firmware Update Using LKS Secure Firmware Resiliency W77751NWDBAE 512 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Firmware Update Using LKS Secure Firmware Update Using LKS Secure Storage Secure Firmware Resiliency Secure Firmware Resiliency NIST 8259A) INST 8259A)	W77Q128JWBAO	128Mb	133	66	2.7	3.6	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025		
W77Q64JWTBAO 64Mb 133 66 2.7 3.6 -40 105 TFBGA-24 (5x5) 5x5-1 mm 4 SPI/Dual/Quad 2025 W77T25NWSBAE 256 Mb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 W77T25NWSBAO 256 Mb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Boot Secure Storage Secure Firmware Update Using LMS Secure Firm	W77Q64JWTBAS	64Mb	133	66	2.7	3.6	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025		
W77T25NWSBAE 266 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Boot Secure Storage Secure Stor	W77Q64JWTBAO	64Mb	133	66	2.7	3.6	-40	105	TFBGA-24 (5x5)	5x5-1 mm	4	SPI/Dual/Quad	2025		
W77725NWSBA0 256 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Boot Secure Storage Secure Storage Secure Storage Secure Storage Secure Storage Secure Storage Secure Firmware Update Using LMS SESIP (with IEC62443-4-2 And NIST 8259A) Secure Storage Secure Stora	W77T25NWSBAE	256 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025		
W77T25NWSBAQ 266 Mb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Storage Secure Firmware Update Using LMS CC EAL2 W77T51NWDBAE 512 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Secure Storage Secure Firmware Update Using LMS CC EAL2 W77T51NWDBAO 512 Mb 200 0.0 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Asymmetric Cryptography And NIST 8259A) ISO 21434 FIPS PUB ISO 21434 FIPS PUB ISO 21434 FIPS PUB 180-3 CMVP W77T01NWQBAE 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Asymmetric Cryptography ISO 21434 FIPS PUB 180-3 CMVP W77T01NWQBAE 1 Gb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Suit-in ECC and SPI CRC for Safety	W77T25NWSBAO	256 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Secure Boot	
W77T51NWDBAE 512 Mb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 PQC SECURE Firmware Update Using LMS SCC EACL W77T51NWDBAO 512 Mb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Asymmetric Cryptography SESIP With IEC62443-4-2 Amountain IST 8 SPI/Quad/Octal 2025 Asymmetric Cryptography SO 21434 FIPS PUB ISO 21434 FIPS PUB ISO 21434 FIPS PUB 180-3 CMVP W77T01NWQBAE 1 Gb 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 PMC ISO 21434 FIPS PUB 180-3 CMVP W77T01NWQBAO 1 Gb 200 2.00 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Built-in ECC and SPI CRC for Safety ISO 21434 FIPS PUB 180-3 CMVP W77T01NWQBAO <td>W77T25NWSBAQ</td> <td>256 Mb</td> <td>200</td> <td>200</td> <td>1.7</td> <td>1.95</td> <td>-40</td> <td>105</td> <td>TFBGA-24 (5x5)</td> <td>5x5-1 mm</td> <td>8</td> <td>SPI/Quad/Octal</td> <td>2025</td> <td>Secure Storage</td> <td>CC FAL2</td>	W77T25NWSBAQ	256 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Secure Storage	CC FAL2
W77T51NWDBAQ 512 Mb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Asymmetric Cryptography ISO 21434 and NIST 8259A) ISO 21434 W77T51NWDBAQ 512 Mb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Platform Firmware Resiliency RPMC NIST 8259A) ISO 21434 FIPS PUB 180-3 CMVP W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Platform Firmware Resiliency Built-in ECC and SPI CRC for Safety And NIST 8259A) W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Asilt-in ECC and SPI CRC for Safety W77T01NWQBAO 1 Gb 200 2.00 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 ASIL-D Ready	W77T51NWDBAE	512 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Secure Firmware Update Using LMS	SESIP (with IEC62443-4-2
W77T51NWDBAQ 512 Mb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Platform Firmware Resiliency ISO 21434 W77T01NWQBAE 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Platform Firmware Resiliency ISO 21434 FIPS PUB 180-3 CMVP W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Built-in ECC and SPI CRC for Safety ISO 21434 W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 ASIL-D Ready ISO 21434 W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 ASIL-D Ready	W77T51NWDBAO	512 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Asymmetric Cryptography	and NIST 8259A)
W77T01NWQBAE 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Built-in ECC and SPI CRC for Safety W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 Built-in ECC and SPI CRC for Safety W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 ASIL-D Ready	W77T51NWDBAQ	512 Mb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Platform Firmware Resiliency	ISO 21434
W77T01NWQBAO 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025 ASIL-D Ready	W77T01NWOBAF	1 Gb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	RPMC	FIPS PUB 180-3 CMVP
The second	W77T01NWOBAO	1 Gb	200	200	17	1.95	-40	105	TEBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	Built-In ECC and SPI CRC for Safety	
W//101NWQBAQ 1 Gb 200 200 1.7 1.95 -40 105 TFBGA-24 (5x5) 5x5-1 mm 8 SPI/Quad/Octal 2025	W77T01NWQBAQ	1 Gb	200	200	1.7	1.95	-40	105	TFBGA-24 (5x5)	5x5-1 mm	8	SPI/Quad/Octal	2025	HOIL D HEAUY	

⁽¹ Certification in progress

Winbond shall have the right to modify the status and schedule of this product at any time without notice.

W75F Secure Memory Element

The 4Mb, 16Mb or 32Mb W75F provides the industry's most secure and safe external storage solution for code and data in applications such as payments, iSIM cards, system security, biometric, eIDs and automotive modules. It defends products against threats such as replay, roll-back, man-in-the-middle, sniffing, side-channel, and fault injection attacks. The W75F can construct a robust and flexible secure memory sub-system with Secure Flash Interface IP of SoC (provided by Winbond) or can be a complementary embedded security system to Arm[®]v8-M architecture-based systems. Contact Winbond for further details.

Product Line	Description	Main Features and Security Level
W75F	Secure Memory Element	High: • ISO 15408 CC EAL 5+ • ISO 26262 ASIL-D Ready • PSA Certified Level 2 Ready • ISO 21434 Automotive Cybersecurity • SESIP Level 3 + Physical Attack Resistance and Software Attacker Resistance: Isolation of Platform • Compliant with 3S in SoC Protectio Profile PP0117 for Integrated SE and SIM Functionality
	SoC	W75F Bus encryption Encrypted storage
	Replay attack Roll-back attack Sniffing attack	Integrity check Side channel attack Fault injection attack Man-in-the-middle attack

Industrial Grade Support

Part No.	Density (Mb)	STR Frequency (MHz)	DTR Frequency (MHz)	Operating Voltage (min) (V)	Operating Voltage (max) (V)	Operating Temp. (min) (°C)	Operating Temp. (max) (°C)	Package Type	Dimension	VO (bit)	Interface Type	Mass Production	Security Features	Security Certifications
W75F32WBYWBG	32	50	-	1.65	1.95	-25	85	WLCSP-15	-	8	SPI/Quad/Octal			
W75F32WBYWCG	32	50	-	1.65	1.95	-25	85	WLCSP-15	-	8	SPI/Quad/Octal	V		
W75F32WBYIBG	32	50	-	1.65	1.95	-40	85	WLCSP-15	-	8	SPI/Quad/Octal	V		
W75F32WBYICG	32	50	-	1.65	1.95	-40	85	WLCSP-15	-	8	SPI/Quad/Octal		Meets CC EAL5+ Security	
W75F32WBYJBG	32	50	-	1.65	1.95	-40	105	WLCSP-15	-	8	SPI/Quad/Octal	V	Certification Requirements	
W75F32WBYJCG	32	50	-	1.65	1.95	-40	105	WLCSP-15	-	8	SPI/Quad/Octal		Secure eXecute-in-Place (XiP)	
W75F40WBYWDG	4	50	-	1.62	1.98	-25	85	WLCSP-12	-	8	SPI/Quad/Octal	V	Tamper and SCA/DPA Resistant	· CC EAL 5+
W75F40WBYWEG	4	50	-	1.62	1.98	-25	85	WLCSP-12	-	8	SPI/Quad/Octal		Code and Data Confidentiality	PSA Certified Level 2 Ready
W75F40WBYIDG	4	50	-	1.62	1.98	-25	85	WLCSP-12	-	8	SPI/Quad/Octal	V	Mutual Authentication with SoC	SESIP Level 3 + Physical
W75F40WBYIEG	4	50	-	1.62	1.98	-25	85	WLCSP-12	-	8	SPI/Quad/Octal		Shared Memory Architecture for	Attacker
W75F40WBYJDG	4	50	-	1.62	1.98	-40	105	WLCSP-12	-	8	SPI/Quad/Octal	V	Multiple-domains	ISO 26262 ASIL-D Ready
W75F40WBYJEG	4	50	-	1.62	1.98	-40	105	WLCSP-12	-	8	SPI/Quad/Octal	V	20.5 MByte/sec Secured and	• ISO 21434
W75F40WBYWBG	4	50	-	1.62	1.98	-25	85	WLCSP-12	-	8	SPI/Quad/Octal	V	Authenticated Throughput	
W75F40WBYWCG	4	50	-	1.62	1.98	-25	85	WLCSP-12	-	8	SPI/Quad/Octal	V	100,000 Program/Erase Cycles 20-year Data Retention	
W75F40WBYIBG	4	50	-	1.62	1.98	-40	85	WLCSP-12	-	8	SPI/Quad/Octal	V	20-year Data Heternion	
W75F40WBYICG	4	50	-	1.62	1.98	-40	85	WLCSP-12	-	8	SPI/Quad/Octal	V		
W75F40WBYJBG	4	50	-	1.62	1.98	-40	105	WLCSP-12	-	8	SPI/Quad/Octal	V		
W75F40WBYJCG	4	50	-	1.62	1.98	-40	105	WLCSP-12	-	8	SPI/Quad/Octal			

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About Winbond

Winbond Electronics Corporation is a total memory solution provider. The Company provides customer-driven memory solutions backed by the expert capabilities of product design, R&D, manufacturing, and sales services. Winbond's product portfolio, consisting of Customized Memory Solution, Code Storage Flash, and TrustME[®] Secure Flash, is widely used by tier-1 customers in communication, consumer electronics, automotive and industrial, and computer peripheral markets. Winbond is headquartered in Central Taiwan Science Park (CTSP), and it has subsidiaries in the USA, Japan, Israel, China and Hong Kong, and Germany. Based on Taichung and Kaohsiung 12-inch fabs in Taiwan, Winbond keeps pace to develop in-house technologies to provide high-quality memory IC products.





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